



## Application

- Data Center & Networking Equipment
- Servers/Storage Devices
- High Performance Computing (HPC)
- Switches/Routers
- Telecom Central Offices (CO)
- Test And Measurement Equipment

## Standards Compliance

- Compliant with OSFP MSA Rev 4.1
- Compliant with IEEE 802.3cd
- Compliant with IEEE 802.3bj
- I2C for EEPROM communication
- Compliant with CMIS 5.0

## Highlight

- Support 8x56G PAM4
- 400G To 400G Data Rate
- 3.3V Power Supply
- Hot Pluggable
- Excellent SI Performance
- RoHS Compliance
- Simplifies The Patching And Offers A Cost-Effective Way For Short Links

1.0 General Description

This datasheet pertains to the **OSFP 400G Direct Attached Copper Cable Assembly**, meticulously designed for application in the telecommunications and data center sectors. It facilitates bi-directional transmission of 400Gb traffic per cable, accommodating 8 lanes of 50G PAM4. The cable adheres to the standardized OSFP form factor and complies rigorously with Multi-Source Agreement (MSA) specifications.

2.0 Product Specification

2.1 Absolute Maximum Ratings

Parameter	Unit	Min.	Max.	Notes
Supply Voltage	V	-0.3	3.6	
Data Input Voltage	V	-0.3	3.6	
Control Input Voltage	V	-0.3	3.6	
Operating Temperature	°C	0	70	
Storage Temperature	°C	-40	+85	
Relative Humidity (Non-Condensing)	%	5	85	

2.2 Operational Specification

Parameter	Unit	Min	Typical	Max	Notes
Supply Voltage (Vcc)	V	3.135	3.3	3.465	Per End
Power Consumption	W			1.5	Per End
Operating Case Temperature	°C	0		70	
Operating Relative Humidity	%	0		85	
Modulation Format		56G PAM-4			
Bit Rate	Gbps	8x50G to 8x50G			

2.3 Electrical Characteristics

Parameter	Unit	Min	Typical	Max	Notes
Characteristic Impedance	ohm	90	100	110	
Time Propagation Delay (Informative)	ns	.....	.....	4.9	

## 2.4 SI performance

Item	Parameter	Require	Reference
1	ILdd Insertion loss at 13.28 GHz	17.16 dB (Max.)	IEEE 802.3cd Section Section 136.11.2
2	ILdd Insertion loss at 13.28 GHz	8 dB (Min.)	IEEE 802.3cd Section Section 136.11.2
3	ERL Minimum cable assembly	>11 dB*.	IEEE 802.3cd Section Section 136.11.3
4	RLcd Differential-mode to common-mode return loss	0.01GHz – 19GHz Equation (92–28)	IEEE 802.3cd Section 136.11.4
5	ILcd Differential-mode to common-mode insertion loss	0.01GHz – 19GHz Equation (92–29)	IEEE 802.3cd Section 136.11.5
6	RLcc Common-mode to common-mode return loss	0.01GHz – 19GHz Equation (92–30)	IEEE 802.3cd Section Section 136.11.6
7	COM	3dB (Min.)	IEEE 802.3ck Section 162.11.7
*Cable assemblies with a com greater than 4 dB are not required to meet minimum ERL			

## 2.5 Pin Assignments

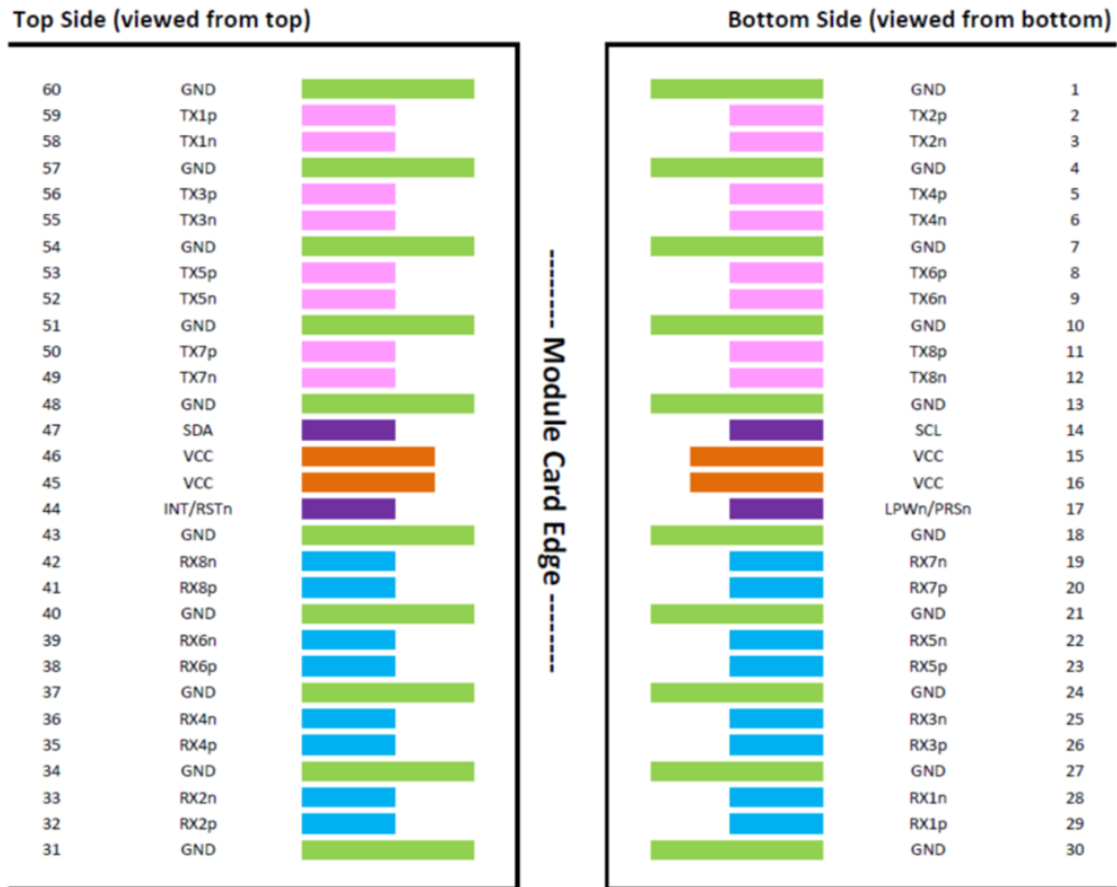


Figure 1 OSFP Module Contact Assignment

## 2.6 Pin Description

Table 1 OSFP-RHS Module Pin Description

Pin	Logic	Symbol	Description	Plug Sequence	Notes
1		GND	Ground	1	
2	CML-I	TX2p	Transmitter Data Non-Inverted	3	
3	CML-I	TX2n	Transmitter Data Inverted	3	
4		GND	Ground	1	
5	CML-I	TX4p	Transmitter Data Non-Inverted	3	
6	CML-I	TX4n	Transmitter Data Inverted	3	
7		GND	Ground	1	
8	CML-I	TX6p	Transmitter Data Non-Inverted	3	
9	CML-I	TX6n	Transmitter Data Inverted	3	
10		GND	Ground	1	
11	CML-I	TX8p	Transmitter Data Non-Inverted	3	
12	CML-I	TX8n	Transmitter Data Inverted	3	

13		GND	Ground	1	
14	LVC MOS-I/O	SCL	2-wire Serial interface clock	3	1
15		VCC	+3.3V Power	2	
16		VCC	+3.3V Power	2	
17	Multi-Level	LPWn/PRSn	Low-Power Mode / Module Present	3	2
18		GND	Ground	1	
19	CML-O	RX7n	Receiver Data Inverted	3	
20	CML-O	RX7p	Receiver Data Non-Inverted	3	
21		GND	Ground	1	
22	CML-O	RX5n	Receiver Data Inverted	3	
23	CML-O	RX5p	Receiver Data Non-Inverted	3	
24		GND	Ground	1	
25	CML-O	RX3n	Receiver Data Inverted	3	
26	CML-O	RX3p	Receiver Data Non-Inverted	3	
27		GND	Ground	1	
28	CML-O	RX1n	Receiver Data Inverted	3	
29	CML-O	RX1p	Receiver Data Non-Inverted	3	
30		GND	Ground	1	
31		GND	Ground	1	
32	CML-O	RX2p	Receiver Data Non-Inverted	3	
33	CML-O	RX2n	Receiver Data Inverted	3	
34		GND	Ground	1	
35	CML-O	RX4p	Receiver Data Non-Inverted	3	
36	CML-O	RX4n	Receiver Data Inverted	3	
37		GND	Ground	1	
38	CML-O	RX6p	Receiver Data Non-Inverted	3	
39	CML-O	RX6n	Receiver Data Inverted	3	
40		GND	Ground	1	
41	CML-O	RX8p	Receiver Data Non-Inverted	3	
42	CML-O	RX8n	Receiver Data Inverted	3	
43		GND	Ground	1	
44	Multi-Level	INT/RSTn	Module Interrupt / Module Reset	3	2
45		VCC	+3.3V Power	2	
46		VCC	+3.3V Power	2	
47	LVC MOS-I/O	SDA	2-wire Serial interface data	3	1
48		GND	Ground	1	
49	CML-I	TX7n	Transmitter Data Inverted	3	
50	CML-I	TX7p	Transmitter Data Non-Inverted	3	
51		GND	Ground	1	
52	CML-I	TX5n	Transmitter Data Inverted	3	
53	CML-I	TX5p	Transmitter Data Non-Inverted	3	
54		GND	Ground	1	

55	CML-I	TX3n	Transmitter Data Inverted	3	
56	CML-I	TX3p	Transmitter Data Non-Inverted	3	
57		GND	Ground	1	
58	CML-I	TX1n	Transmitter Data Inverted	3	
59	CML-I	TX1p	Transmitter Data Non-Inverted	3	
60		GND	Ground	1	
Note 1: Open-Drain with pull- up resistor on Host.					
Note 2: See pin description for required circuit					

WIRING TABLE

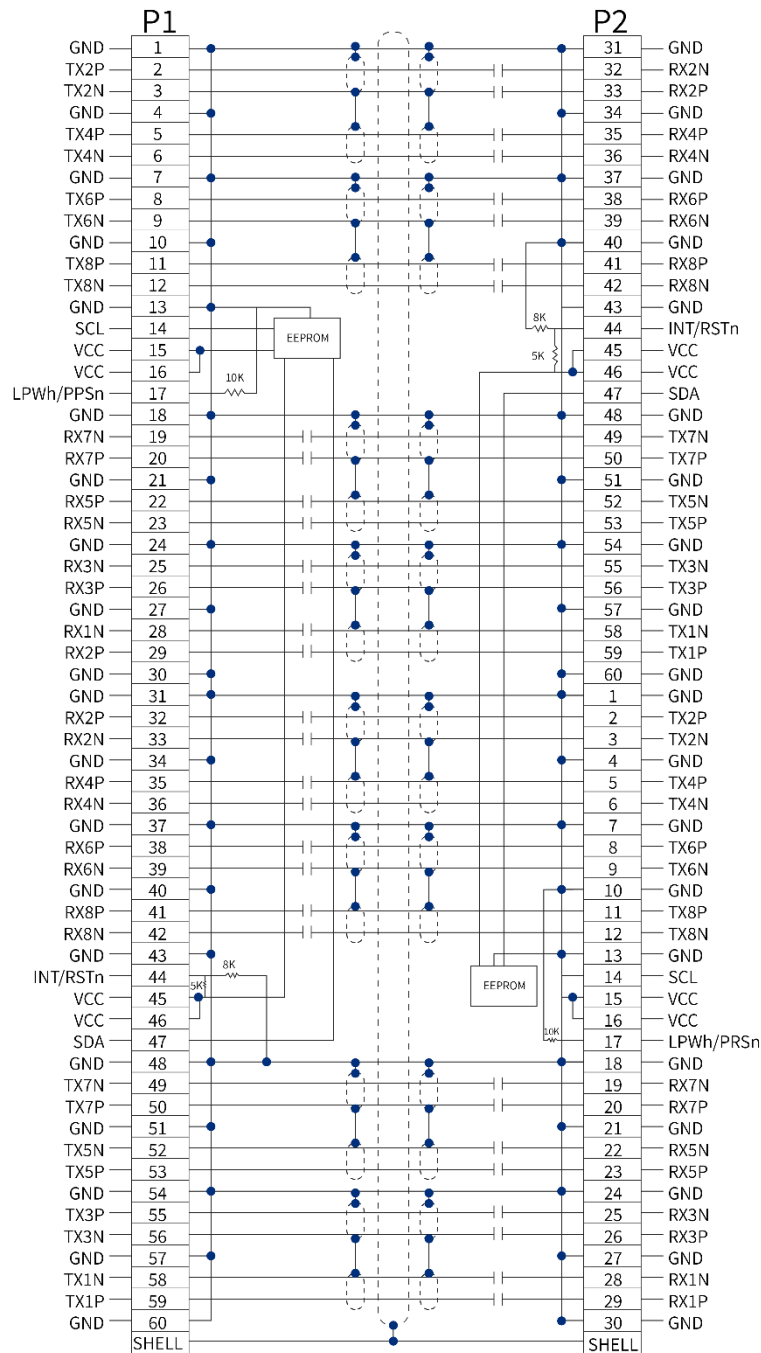


Figure 2 OSFP 400G Direct Attached Cable Assembly Wiring

## 2.8 Memory Map information (CMIS Version)

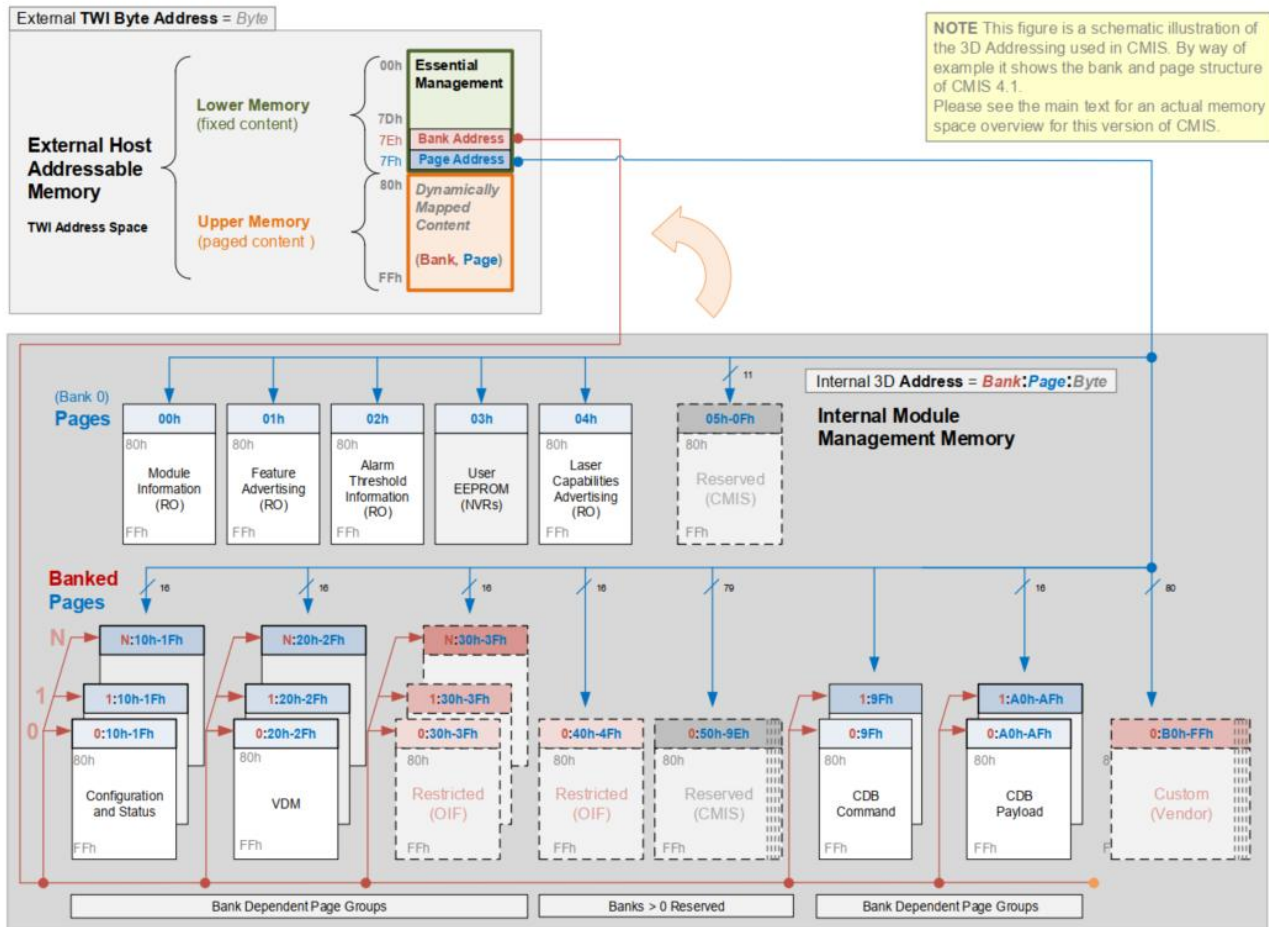


Figure 3 CMIS Module Memory Map (Conceptual View)

## ■ Lower Memory Overview

Address	Size	Subject Area	Description
0-3	4	ID and Status Area	Module ID from SFF-8024 list, version number, Type and status Flat mem indication, CLEI present indicator, Maximum TWI speed, Current state of Module, Current state of the Interrupt signal
4-7	4	Lane Flag Summary	Flag summary of all lane flags on pages 10h-1Fh
8-13	6	Module-Level Flags	All flags that are not lane or data path specific
14-25	12	Module-Level Monitors	Monitors that are not lane or data path specific
26-3	5	Module Global Controls	Controls applicable to the module as a whole
31-36	6	Module-Level Flag Masks	Masking bits for the Module-Level flags
37-38	2	CDB Status Area	Status of most recent CDB command
39-40	2	Module Firmware Version	Module Firmware Version
41-63	23	Reserved Area	Reserved for future standardization
64-82	19	Custom Area	Vendor or module type specific use
83-84	2	Inactive Firmware Version	Version Number of Inactive Firmware. Values of



			00h indicates module supports only a single image.
85-117	33	Application Advertising	Combinations of host and media interfaces that are supported by module data path(s)
118-125	8	Password Entry and Change	
126	1	Bank Select Byte	Bank address of currently visible Page
127	1	Page Select Byte	Page address of currently visible Page

#### ■ [Page 00h Overview](#)

Address	Size (bytes)	Name	Description
128	1	Identifier	Identifier Type of module
129-144	16	Vendor name	Vendor name (ASCII)
145-147	3	Vendor OUI	Vendor IEEE company ID
148-163	16	Vendor PN	Part number provided by vendor (ASCII)
164-165	2	Vendor rev	Revision level for part number provided by vendor (ASCII)
166-181	16	Vendor SN	Vendor Serial Number (ASCII)
182-189	8	Date Code	
190-199	10	CLEI code	Common Language Equipment Identification code
200-201	2	Module power characteristics	
202	1	Cable assembly length	
203	1	Media Connector Type	
204-209	6	Copper Cable Attenuation	
210-211	2	Cable Assembly Lane Information	
212	1	Media Interface Technology	
213-220	8	Reserved	
221	1	Custom	
222	1	Checksum	Includes bytes 128-221
223-255	33	Custom Info NV	

Note: For the above, refer to **Common Management Interface Specification Rev5.0**.

2.9 Mechanical Specifications

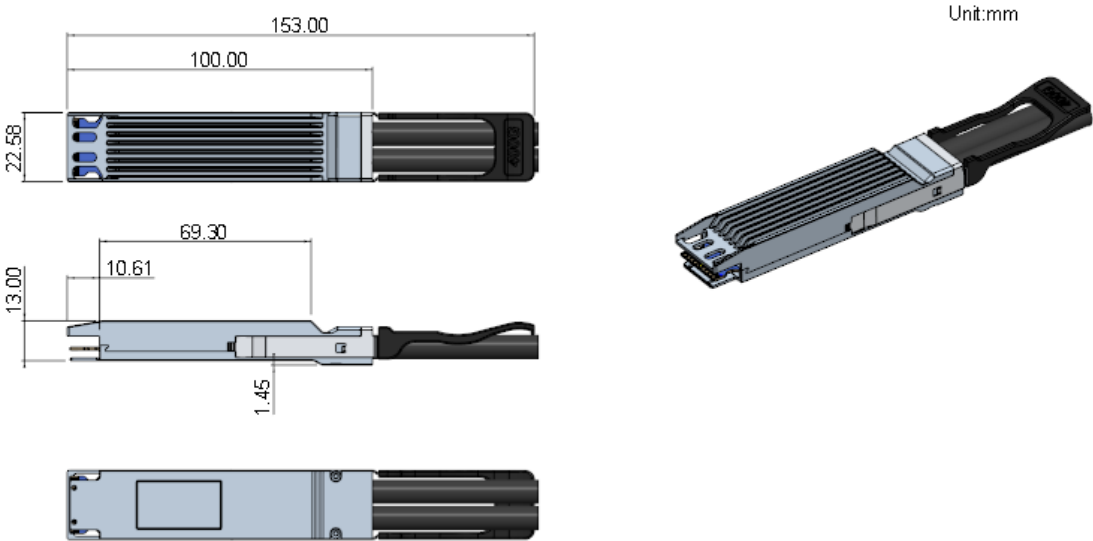
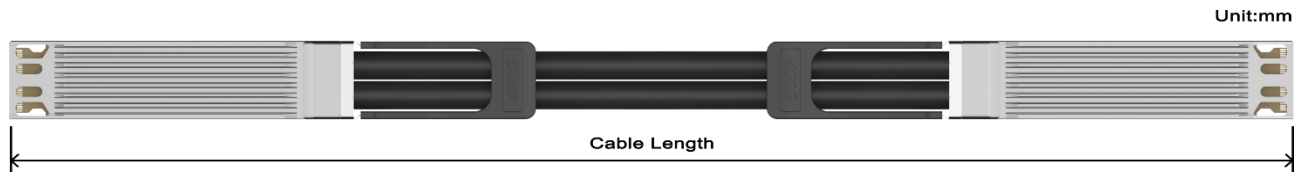


Figure 4 OSFP Form Factor

### 3.0 Product Information



Product ID	Product Description	Tolerance	AWG
OSFP 400G-DAC-3005	OSFP 400G Direct Attached Copper Cable, 30AWG-0.5M	±20	30
OSFP 400G-DAC-3010	OSFP 400G Direct Attached Copper Cable, 30AWG-1.0M	±30	30
OSFP 400G-DAC-3015	OSFP 400G Direct Attached Copper Cable, 30AWG-1.5M	±40	30
OSFP 400G-DAC-3020	OSFP 400G Direct Attached Copper Cable, 30AWG-2.0M	±40	30
OSFP 400G-DAC-2820	OSFP 400G Direct Attached Copper Cable, 28AWG-2.0M	±40	28
OSFP 400G-DAC-2825	OSFP 400G Direct Attached Copper Cable, 28AWG-2.5M	±50	28
OSFP 400G-DAC-2625	OSFP 400G Direct Attached Copper Cable, 26AWG-2.5M	±50	26
OSFP 400G-DAC-2630	OSFP 400G Direct Attached Copper Cable, 26AWG-3.0M	±50	26

#### Important Notice

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4.0Revision Record

Rev.	Comments	Author	Date
A01	Initial Release	James Chen	10/01/2023